PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Hideharu TAKEUCHI	10/08/2009
Kouki HAMATA	10/08/2009
Masaki KOBAYASHI	10/08/2009
Minoru MURATA	10/08/2009
Takahiro KOSHIMIZU	10/08/2009

RECEIVING PARTY DATA

Name:	ARAKAWA CHEMICAL INDUSTRIES, LTD.	
Street Address:	1-3-7, Hirano-machi, Chuo-ku	
City:	Osaka-shi, Osaka	
State/Country:	JAPAN	
Postal Code:	541-0046	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12600442

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	Garth M. Dahlen, Ph.D.

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PATENT REEL: 023531 FRAME: 0095

BIRCH, STEWART, KOLASCH & BIRCH, LLP

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ASSIGNMENT

Application No.	12/600,442	Filed	November	16,	2009
Insert Namc(s) of Inventor(s)	***(Given Name FAMILY NAME (ALL CAPS))***				
.,	WHEREAS, Hideharu TAKEUCHI; Kouki HAM Takahiro KOSHIMIZU (hereinafter designated as useful improvements in:	ATA; Ma the under	saki KOBAYASH rsigned) has (have	II; Minc) invent	oru MURATA; and ed certain new and
Insert Title of Invention	OPTICAL SEMICONDUCTOR-SEALING COM	POSITIO	N		
	for which an application for Letters Patent of the undersigned (except in the case of a provisional application).			has bee	en executed by the
Insert Date of Signing of	onOctober 8, 2009	9			; and
Application Insert Name of Assignee	WHEREAS, ARAKAWA CHEMICAL INDUS	TRIES, L	TD.		
Insert Address of Assignee CHECK BOX IF APPROPRIATE	of 1-3-7, Hirano-machi, Chuo-ku, Osaka-shi Osak	a, 541-00	46, JAPAN		
	its heirs, successors, legal representatives and desirous of acquiring the entire right, title and interpatent(s) that may be granted therefor in the Unite x in any foreign countries.	rest in an	d to said invention		
	NOW, THEREFORE, in consideration of the sun paid, the receipt of which is hereby acknowledge undersigned has (have) sold, assigned and transfer unto said Assignee the full and exclusive America, its territories, dependencies and possessions and all Letters Patent(s) which may be graterritories, dependencies and possessions, and if countries;	ged, and sferred, and se right to sions and anted the	other good and v nd by these prese the said invention the entire right, t refor in the Unite	aluable onts doe on in the itle and ed State	consideration, the es sell, assign and e United States of interest in and to es of America, its
	and to any and all divisions, reissues, continuati term or terms for which the same may be granted.	ons, conv	versions and exter	nsions t	hereof for the full

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree (s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Birch, Stewart, Kolasch & Birch, LLP the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date _	October 8, 2009	Name of Inventor <u>Wideharu Takenchi</u>
		(signature) Hideharu TAKEUCHI
Date _	October 8, 2009,	Name of Inventor Konki Humata
		(signature) Kouki HAMATA
Date _	October 8, 2009,	Name of Inventor
		(signature) Masaki KOBAYASHI
Date _	October 8, 2009,	Name of Inventor Minory Murater
		(signature) Minoru MURATA
Date _	October 8, 2009,	Name of Inventor <u>Jakahira Koshimigu</u> (signature) Takahiro KOSHIMIZU
		(signature) Takahiro KOSHIMIZU